

congatec Application Note



Applicable Products	All congatec XTX and ETX modules
Application Note Subject	Mechanical mounting solutions for congatec XTX or ETX modules
Document Name	AN14_ETX_XTX_Mounting_Solutions
Usage Designation	External

Application Note #14

Revision 1.3

Revision History

Revision	Date (dd.mm.yy)	Author	Changes
1.0	30.01.07	HCH	Initial release
1.1	21.08.07	HCH	Added additional standoff order numbers.
1.2	23.10.08	HCH	Deleted KVT standoffs (bore hole) because of to big outer diameter and EFCO ECM00512-L because of EOL
1.3	28.12.10	HCH	Updated document format; Corrected minor mistakes

Preface

This Application Note provides information about the mounting solutions (heatspreader - CPU module – carrier board) that are possible with congatec XTX or ETX modules.

Disclaimer

The information contained within this Application Note, including but not limited to any product specification, is subject to change without notice.

congatec AG provides no warranty with regard to this Application Note or any other information contained herein and hereby expressly disclaims any implied warranties of merchantability or fitness for any particular purpose with regard to any of the foregoing. congatec AG assumes no liability for any damages incurred directly or indirectly from any technical or typographical errors or omissions contained herein or for discrepancies between the product and the Application Note. In no event shall congatec AG be liable for any incidental, consequential, special, or exemplary damages, whether based on tort, contract or otherwise, arising out of or in connection with this Application Note or any other information contained herein or the use thereof.

Intended Audience

This Application Note is intended for technically qualified personnel. It is not intended for general audiences.

Symbols

The following symbols may be used in this Application Note:



Warning

Warnings indicate conditions that, if not observed, can cause personal injury.



Caution

Cautions warn the user about how to prevent damage to hardware or loss of data.



Note

Notes call attention to important information that should be observed.

Electrostatic Sensitive Device



All congatec AG products are electrostatic sensitive devices and are packaged accordingly. Do not open or handle a congatec AG product except at a electrostatic-free workstation. Additionally, do not ship or store congatec AG products near strong electrostatic, electromagnetic, magnetic, or radioactive fields unless the device is contained within its original manufacturer's packaging. Be aware that failure to comply with these guidelines will void the congatec AG Limited Warranty.

Terminology

Some of the following terms may be used throughout this document.

Term	Description
Heatspreader (HSP)	Thermal interface between the module and the application specific thermal solution. The heatspreader should not be considered as a heatsink.
T.B.D.	To be determined

Copyright Notice

Copyright © 2007, congatec AG. All rights reserved. All text, pictures and graphics are protected by copyrights. No copying is permitted without written permission from congatec AG.

congatec AG has made every attempt to ensure that the information in this document is accurate yet the information contained within is supplied "as-is".

Trademarks

Intel and Pentium are registered trademarks of Intel Corporation. Expresscard is a registered trademark of Personal Computer Memory Card International Association (PCMCIA). PCI Express is a registered trademark of Peripheral Component Interconnect Special Interest Group (PCI-SIG). I²C is a registered trademark of Philips Corporation. CompactFlash is a registered trademark of CompactFlash Association. Winbond is a registered trademark of Winbond Electronics Corp. AVR is a registered trademark of Atmel Corporation. ETX is a registered trademark of Kontron AG. AMICORE8 is a registered trademark of American Megatrends Inc. XpressROM is a registered trademark of Insyde Technology, Inc. Microsoft®, Windows®, Windows NT®, Windows CE and Windows XP® are registered trademarks of Microsoft Corporation. VxWorks is a registered trademark of WindRiver. conga, congatec and XTX are registered trademark of congatec AG. All product names and logos are property of their owners.

Contents

1 Introduction.....	6
2 Heatspreader.....	6
3 Mounting Solutions.....	8
3.1 congatec Heatspreader for Top-Mounting Solution.....	8
3.2 congatec Heatspreader for Bottom-Mounting Solution.....	9

1 Introduction

One of the essential tasks for system developers is defining the mounting and securing concept for their embedded computer module application. The system must remain service-friendly yet still be able to handle the harsh (mechanical) environmental conditions industrial applications often face. congatec has taken into consideration the different mechanical requirements and offers adequate solutions. This application note will give examples of mounting possibilities and will describe the parts that are needed to implement these solutions.

2 Heatspreader

The ETX and XTX Embedded Module Specifications defines a thermal interface that can be used to connect the module to a cooling solution. This thermal interface, called a heatspreader, acts as a thermal coupling device between the module and the cooling solution.

This application note will look at the heatspreader from the mechanical side of view. There are other documents available that cover the thermal function of the heatspreader.

The heatspreader is defined in the ETX/XTX Specification as a 2mm thick aluminum plate that is 114mm x 96 mm (the dimensions of an ETX/XTX module is 114mm x 95mm) in size. In each of the 4 corners of the heatspreader there are four 6mm high standoffs. The location of each of these standoffs correspond to the position of each of the 4 corner mounting holes found on the ETX/XTX module. The total height of the heatspreader, measured from the PCB surface of the ETX/XTX module, is 8mm. See picture 1 for heatspreader dimensions.

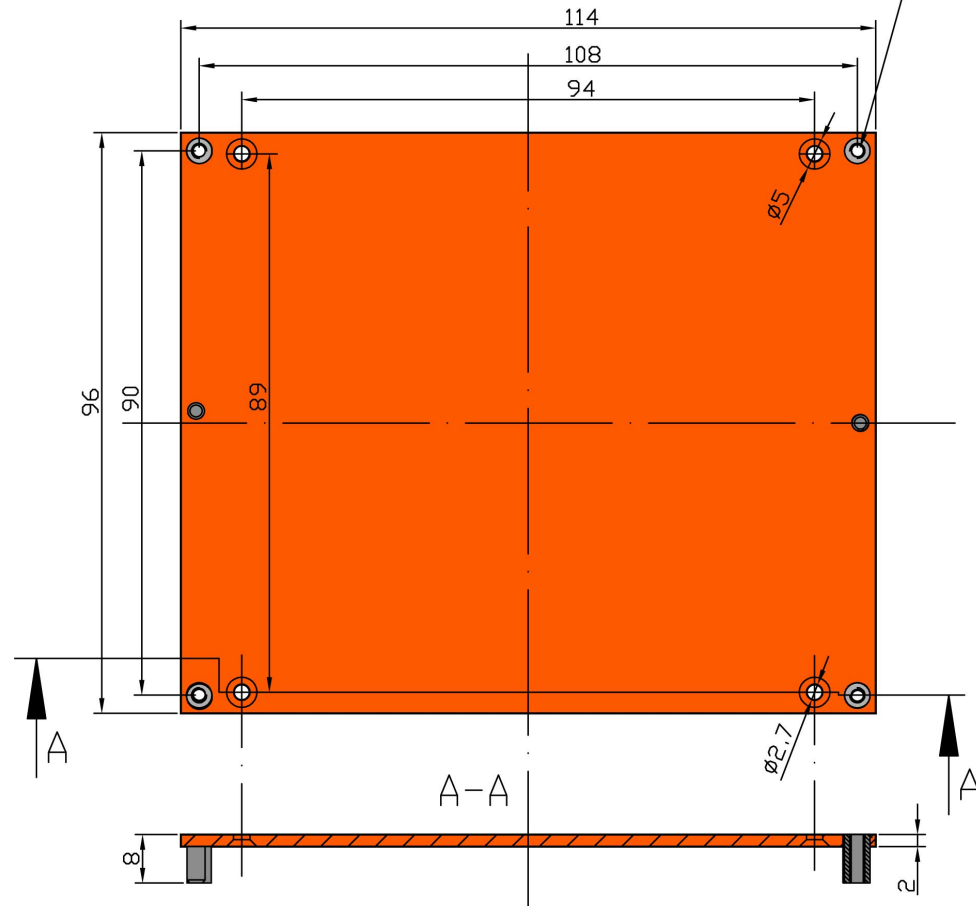
congatec defined additional standoffs and mounting holes for the heatspreader other than the ones defined in the ETX/XTX Specification. The additional standoffs (can be one or more) on the heatspreader should only be used for the mechanical connection between the ETX/XTX module and the heatspreader. These standoffs are necessary for a better thermal connection between the components on the ETX/XTX module and the heatspreader. They should not be used as a connection to the baseboard, the cooling system, or other parts because the position of these standoffs can differ on the different hardware revisions of a product. This is the reason why these additional standoffs are not mentioned in the congatec module User's Guides and not shown in picture 1.

The 4 additional mounting holes in the corners of the heatspreader plate (see picture 1) are always located in the same position on all congatec ETX/XTX heatspreaders. These holes are designed to be used for the mechanical connection between the heatspreader plate and the cooling solution (heatsink, fan, system chassis, heat pipes, etc...). Only these mounting holes should be used to attach the heatspreader to the cooling solution.

 **Note**

The heatspreader is not to be considered as a heatsink. It has been designed to be used as a thermal interface between the module and the application specific thermal solution.

4-M2.5x8mm
threaded standoff
for threaded version
or
4- \varnothing 2.7x8mm
nonthreaded
standoff
for bore hole version



 **Note**

All measurements are in millimeters. Torque specification for heatspreader screws is 0.5 Nm.

Picture 1: Heatspreader dimensions

3 Mounting Solutions

The main mechanical mounting solutions for systems based on ETX or XTX modules have proven to be the 'top-mounting' and 'bottom-mounting' solutions. The decision as to which solution will be used is determined by the mechanical construction and the cooling solution of the customer's system. congatec offers two variants of the heatspreader, one for each mounting possibility. One version has threaded standoffs and the other has non-threaded standoffs (bore hole). The following sections describe these two common mounting possibilities and the additional components (standoffs, screws, etc...) that are necessary to implement the respective solution.

3.1 congatec Heatspreader for Top-Mounting Solution

This variant of the heatspreader was designed to be used in a system where the heatspreader screws need to be inserted from the top side of the complete assembly. In this case the threads for securing the screws are in the carrier board's standoffs. This is the reason why the heatspreader must have non-threaded (bore hole) (HSP-B) standoffs. See Picture 2.



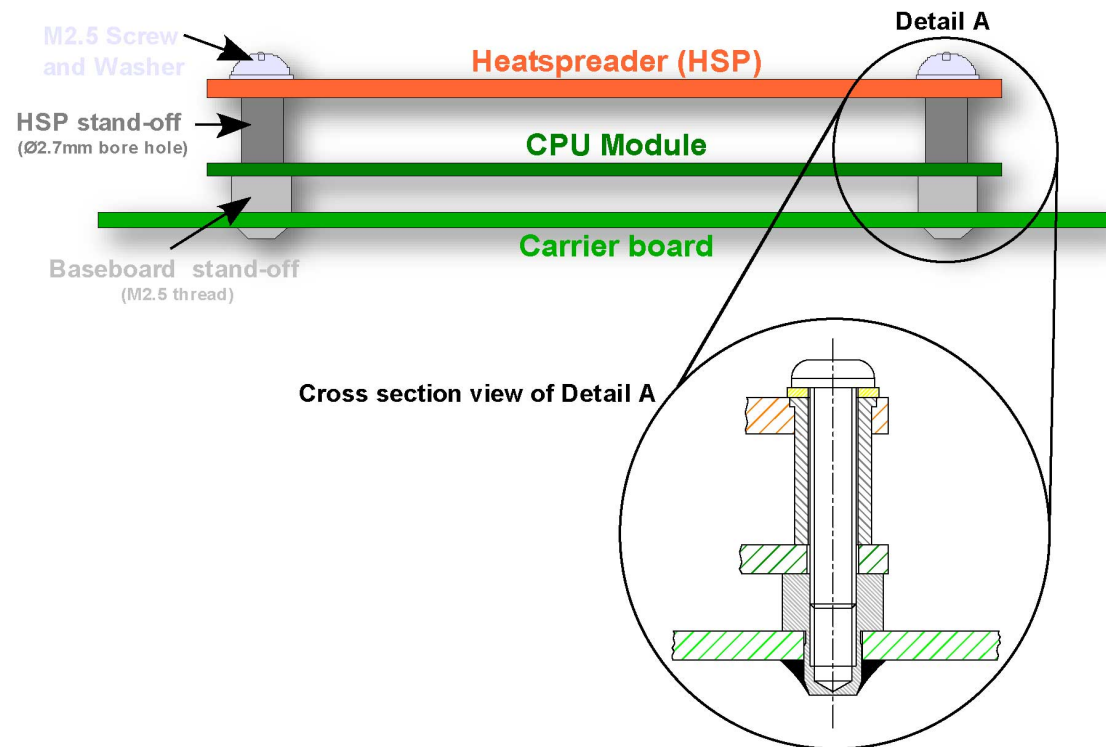
Note

The torque specification for heatspreader screws is 0.5 Nm.



Caution

Do not use a threaded heatspreader together with threaded carrier board standoffs. The combination of the two threads may be staggered, which could lead to stripping or cross-threading of the threads in either the standoffs of the heatspreader or carrier board.



Picture 2: Complete assembly using non-threaded (bore hole) heatspreader

Materials Used for Top-Mounting

Qty	Description	Manufacturer	Manufacturer order number	Comment
1	Heatspreader	congatec	conga-????/HSP-B	Heatspreader standoff with Ø2.7mm bore hole (non-threaded)
4	Carrier board standoff	Everfine Industrial Corp. (www.efcotec.com)	ECM00477-L	Standoff for soldered mounting 3mm height, M2.5 thread
			ECM00247-L	Standoff for press-in mounting 3mm height, M2.5 thread
		Kerb-Konus GmbH (www.kerbkonus.de)	503 600 025.100	Standoff for press-in mounting 3mm height, M2.5 thread
4	Screw M2.5 x 12mm	various	-	Recessed raised cheese head screw with point, galvanized with metric thread M2.5 and 12mm length DIN7985 / ISO7045
4	Washer Ø2.7mm	various	-	Plain washer galvanized for M2.5 screws. DIN433 / ISO7092

3.2 congatec Heatspreader for Bottom-Mounting Solution

The second variant of the heatspreader has been designed to be used in systems where the heatspreader screws need to be inserted from the bottom side of the complete assembly. For this solution a heatspreader version with threaded standoffs (HSP-T) must be used. In this case, the standoffs used on the carrier board are not threaded. See Picture 3.



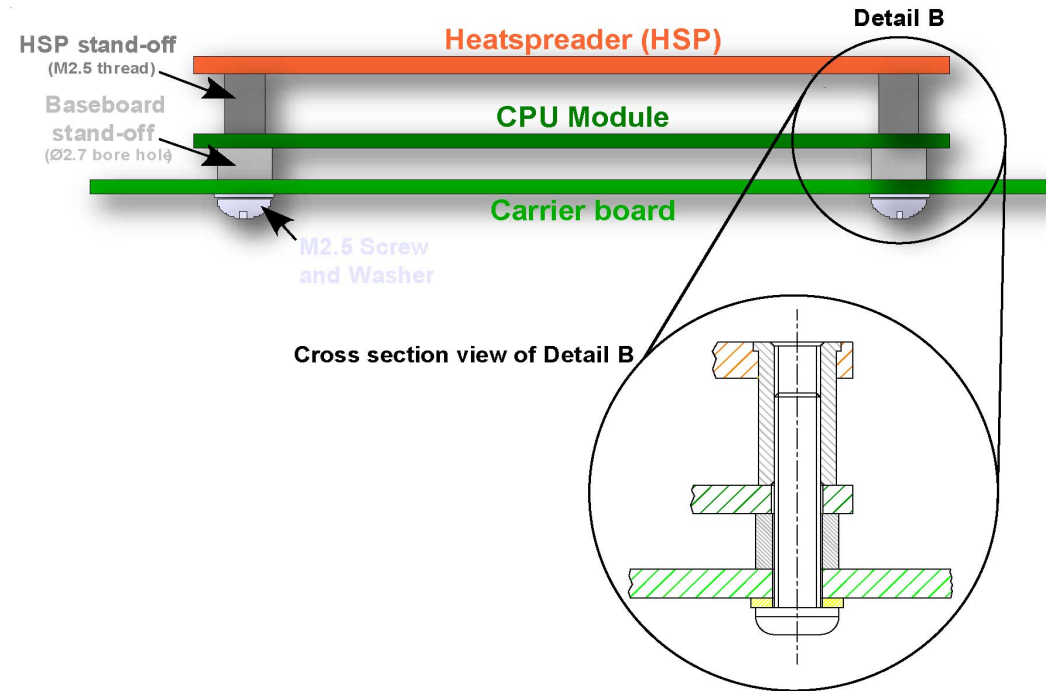
Note

The torque specification for heatspreader screws is 0.5 Nm.



Caution

Do not use a threaded heatspreader together with threaded carrier board standoffs. The combination of the two threads may be staggered, which could lead to stripping of the threads in either the standoffs of the heatspreader or carrier board.



Picture 3: Complete assembly using threaded heatspreader

Materials Used for Bottom-Mounting

Qty	Description	Manufacturer	Manufacturer order number	Comment
1	Heatspreader	congatec	conga-????/HSP-T	Heatspreader standoff with M2.5 thread
4	Carrier board standoff	Everfine Industrial Corp. (www.efcotec.com)	ECM00517-L	Standoff for press-in mounting 3mm height, Ø2.7 mm bore hole
		KVT GmbH (www.kvt-koenig.de)	SMTSO-3.6-3 ET	Standoff for soldered mounting 3mm height, Ø3.6mm bore hole
			KFE-3.6-3 ET	Standoff for press-in mounting 3mm height, Ø3.6mm bore hole
4	Screw M2.5 x 12mm	various	-	Recessed raised cheese head screw with point, galvanized with metric thread M2.5 and 12mm length DIN7985 / ISO7045
4	Washer Ø2.7mm	various	-	Plain washer galvanized for M2.5 screws. DIN433 / ISO7092



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.